

HAT2050T

Silicon N Channel Power MOS FET High Speed Power Switching

REJ03G1171-0300

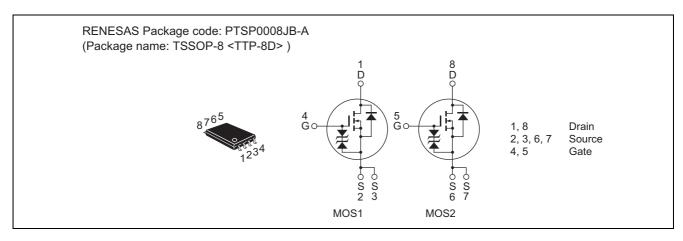
(Previous: ADE-208-660A)

Rev.3.00 Sep 07, 2005

Features

- Low on-resistance
- Capable of 4 V gate drive
- Low drive current
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	100	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	1	A
Drain peak current	I _{D (pulse)} Note 1	4	A
Body-drain diode reverse drain current	I _{DR}	1	A
Channel dissipation	Pch Note 2	1.0	W
Channel dissipation	Pch Note 3	1.5	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

- 2. 1 Drive operation: When using the glass epoxy board (FR4 $40 \times 40 \times 1.6$ mm), PW ≤ 10 s
- 3. 2 Drive operation: When using the glass epoxy board (FR4 $40 \times 40 \times 1.6$ mm), PW ≤ 10 s

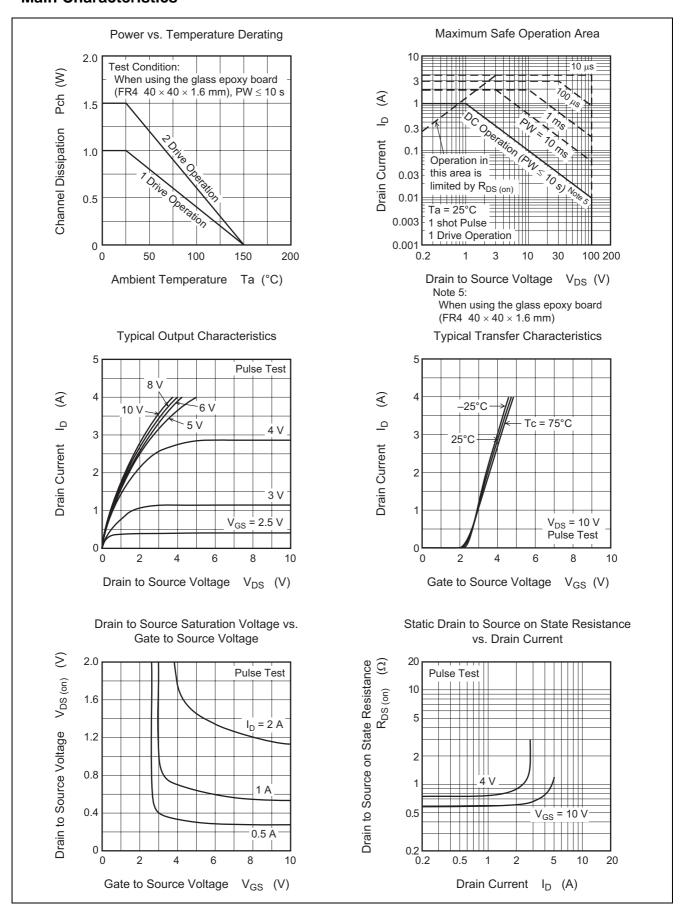
Electrical Characteristics

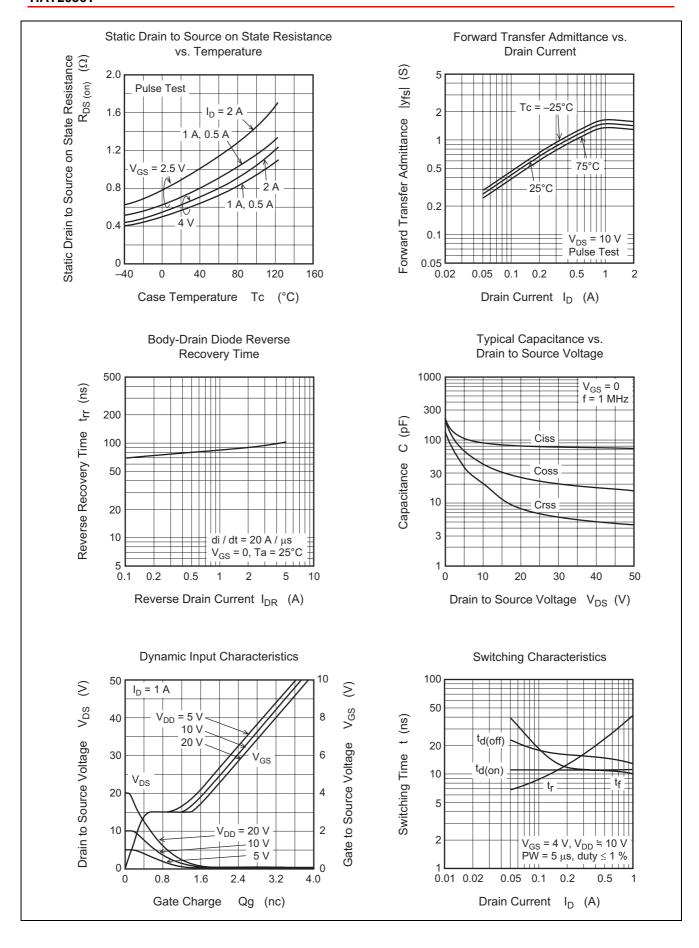
 $(Ta = 25^{\circ}C)$

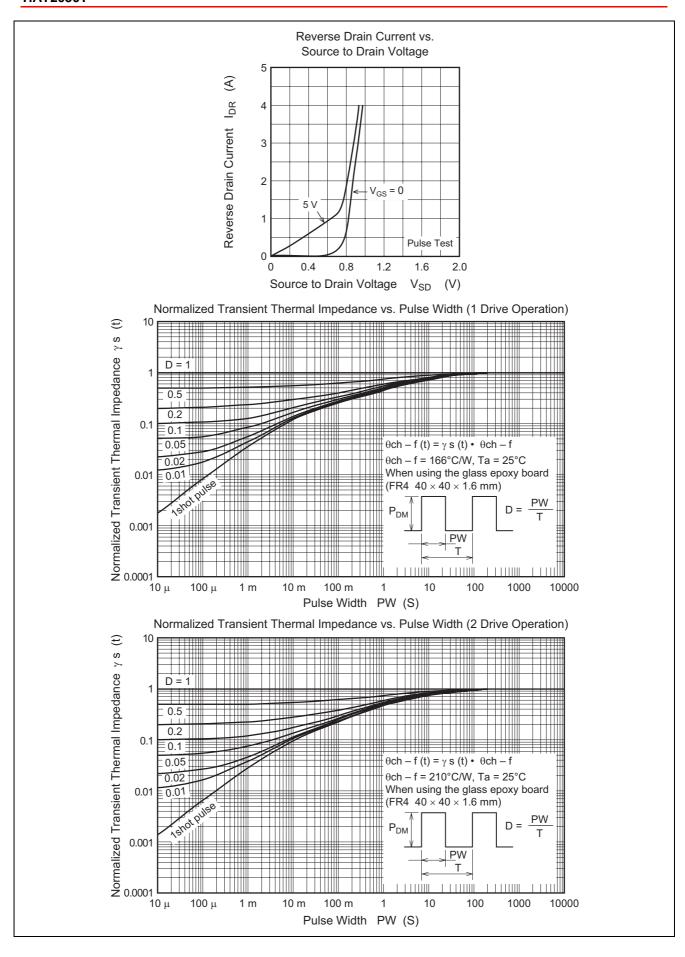
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	100	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR) GSS}	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 100 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	1.3		2.3	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state resistance	R _{DS (on)}	_	0.56	0.75	Ω	$I_D = 0.5 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note 4}}$
	R _{DS (on)}	_	0.72	1.0	Ω	$I_D = 0.5 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note 4}}$
Forward transfer admittance	y _{fs}	0.7	1.1	_	S	$I_D = 0.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 4}}$
Input capacitance	Ciss	_	90	_	pF	V _{DS} = 10 V
Output capacitance	Coss	_	42	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	20	_	pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	_	11	_	ns	$V_{GS} = 4 \text{ V}, I_D = 0.5 \text{ A},$
Rise time	t _r	_	24	_	ns	$V_{DD} \cong 10 \text{ V}$
Turn-off delay time	t _{d (off)}	_	14	_	ns	
Fall time	t _f	_	11	_	ns	
Body-drain diode forward voltage	V_{DF}	_	0.84	1.1	V	$I_F = 1 \text{ A}, V_{GS} = 0^{\text{Note 4}}$
Body-drain diode reverse recovery time	t _{rr}	_	85	_	ns	I _F = 1 A, V _{GS} = 0
						$di_F/dt = 20 A/\mu s$

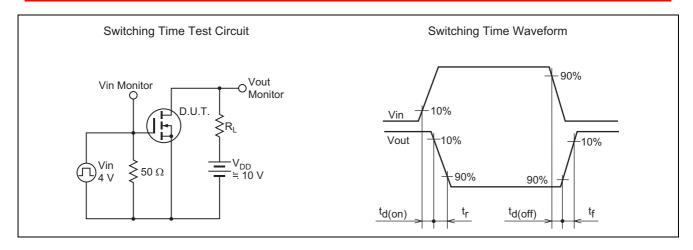
Note: 4. Pulse test

Main Characteristics

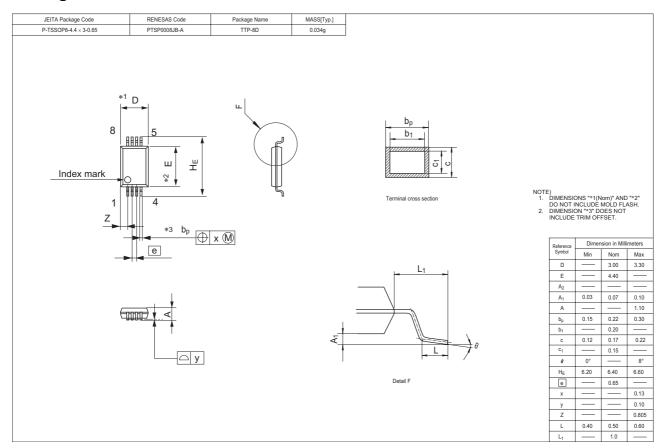








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2050T-EL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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